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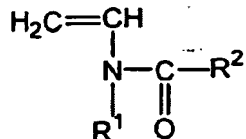
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(54) Title: SEED COATING COMPOSITION, COATED SEED, AND COATING METHOD



containing N-vinylcarboxylic acid amide represented by the following formula (1) and a crosslinking monomer; (1) wherein R<sup>1</sup> is a hydrogen atom, a methyl group or a phenyl group, R<sup>2</sup> is a hydrogen atom, an alkyl group of 1 to 4 carbon atoms or a phenyl group, and R<sup>1</sup> and R<sup>2</sup> may be the same or different.

(57) Abstract: An object of the present invention is to provide a seed coating composition capable of enhancing a germination rate of seeds even in environment where seeds are liable to be dried, a coated seed having been coated with the composition, and a seed coating method. The seed coating composition of the present invention comprises a water absorbing resin and a granulating material, said water absorbing resin being obtained by copolymerizing a monomer mixture

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